



20V P-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BV _{DSS}	RDS(ON)	I _D Max T _A = +25°C
	1.9Ω @ V _{GS} = -4.5V	-0.4A
-20V	2.4Ω @ V _{GS} = -2.5V	-0.36A
	3.4Ω @ V _{GS} = -1.8V	-0.3A

Description and Applications

This MOSFET is designed to minimize the on-state resistance ($R_{DS(ON)}$) yet maintain superior switching performance, making it ideal for high efficiency power management applications.

• Portable electronics

Features and Benefits

- Footprint of just 0.6mm² 13 times smaller than SOT23
- 0.4mm Profile Ideal for Low Profile Applications
- Low Gate Threshold Voltage
- Fast Switching Speed
- ESD Protected
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/104/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please <u>contact us</u> or your local Diodes representative. https://www.diodes.com/quality/product-definitions/

Mechanical Data

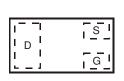
- Package: X2-DFN1006-3
- Package Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish NiPdAu over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (4)
- Weight: 0.001 grams (Approximate)



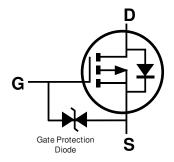




Bottom View



Top View Internal Schematic



Equivalent Circuit

Ordering Information (Note 4)

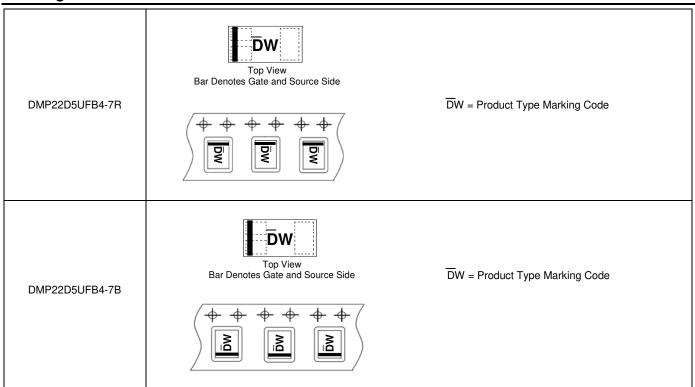
Part Number	Dookogo	Marking	Reel Size (inches)	Tape Width (mm)	Tape Pitch (mm)	Packing	
Part Nulliber	Package	rage Marking Reel Size (Inches) Tape Width		rape widin (iiiii)	itii (iiiiii) Tape Pitcii (iiiiii)		Carrier
DMP22D5UFB4-7R	X2-DFN1006-3	DW	7	8	4	3,000	Reel
DMP22D5UFB4-7B	X2-DFN1006-3	DW	7	8	2	10,000	Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/



Marking Information





Maximum Ratings ($@T_A = +25^{\circ}C$, unless otherwise specified.)

Characteristi		Symbol	Value	Unit	
Drain-Source Voltage			V _{DSS}	-20	V
Gate-Source Voltage			V _{GSS}	±8	V
Continuous Drain Current (Note 6)	Steady State	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	lo	-0.4 -0.32	Α
Maximum Continuous Body Diode Forward Current (Note 6)			Is	-0.4	Α
Pulsed Drain Current (Note 7)			I _{DM}	-0.8	A

Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P _D	0.46	W
Thermal Resistance, Junction to Ambient (Note 5)	Reja	272.1	°C/W
Power Dissipation (Note 6)	PD	1.18	W
Thermal Resistance, Junction to Ambient (Note 6)	Reja	106.2	°C/W
Operating and Storage Temperature Range	TJ, TSTG	-55 to +150	°C

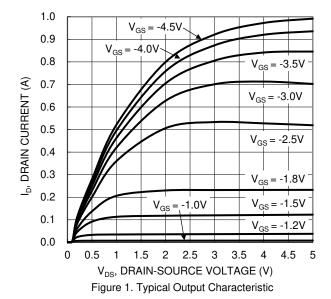
Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 8)							
Drain-Source Breakdown Voltage	BV _{DSS}	-20		_	V	$V_{GS} = 0V, I_{D} = -250\mu A$	
Zero Gate Voltage Drain Current T _J = +25°C	IDSS	_	_	-1	μA	$V_{DS} = -16V$, $V_{GS} = 0V$	
Gate-Source Leakage	Igss	_	_	±10	μΑ	$V_{GS} = \pm 5V$, $V_{DS} = 0V$	
ON CHARACTERISTICS (Note 8)							
Gate Threshold Voltage	V _{GS(TH)}	-0.4	_	-1.0	V	$V_{DS} = V_{GS}$, $I_D = -250\mu A$	
				1.9		$V_{GS} = -4.5V$, $I_{D} = -100mA$	
Static Drain-Source On-Resistance	Dagger		_	2.4	Ω	$V_{GS} = -2.5V, I_{D} = -50mA$	
Static Drain-Source On-Nesistance	Rds(on)	_		3.4		$V_{GS} = -1.8V, I_{D} = -20mA$	
				5		$V_{GS} = -1.5V, I_{D} = -10mA$	
Diode Forward Voltage	V _{SD}	_	_	-1.1	V	$V_{GS} = 0V, I_{S} = -10mA$	
DYNAMIC CHARACTERISTICS (Note 9)							
Input Capacitance	Ciss		17		рF	45)()(
Output Capacitance	Coss		4.1	_	pF	$V_{DS} = -15V, V_{GS} = 0V,$ f = 1.0MHz	
Reverse Transfer Capacitance	Crss		2.7		рF	71 = 1.0000	
Total Gate Charge	Qg		0.3		nC	V 45V V 10V	
Gate-Source Charge	Q_{gs}		0.04		nC	$V_{GS} = -4.5V, V_{DS} = -10V,$ $I_{D} = -250mA$	
Gate-Drain Charge	Q_{gd}		0.1		nC		
Turn-On Delay Time	td(ON)		7.3	_	ns		
Turn-On Rise Time	tr		20.7	_	ns	$V_{DD} = -15V$, $V_{GS} = -4.5V$,	
Turn-Off Delay Time	tD(OFF)	_	185	_	ns	$R_G = 2\Omega$, $I_D = -200$ mA	
Turn-Off Fall Time	t _F		97	_	ns		

Notes:

- 5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
- 6. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal vias to bottom layer 1inch square copper plate.
- 7. Device mounted on minimum recommended pad layout test board, 10μs pulse duty cycle = 1%.
- 8. Short duration pulse test used to minimize self-heating effect.
- 9. Guaranteed by design. Not subject to product testing.





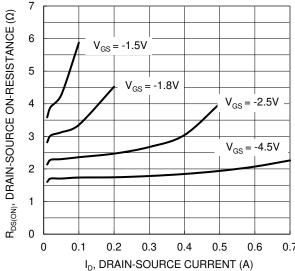


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

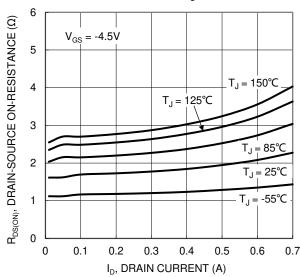


Figure 5. Typical On-Resistance vs. Drain Current and Temperature

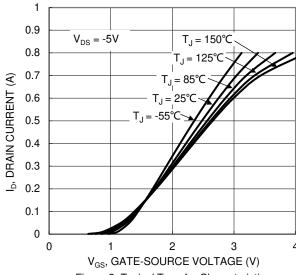


Figure 2. Typical Transfer Characteristic

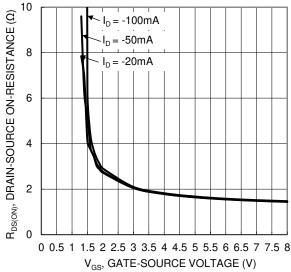


Figure 4. Typical Transfer Characteristic

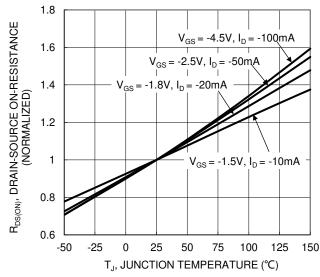


Figure 6. On-Resistance Variation with Temperature



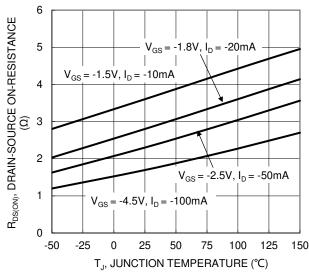


Figure 7. On-Resistance Variation with Temperature

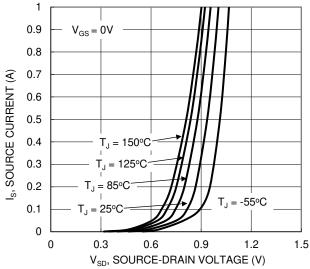


Figure 9. Diode Forward Voltage vs. Current

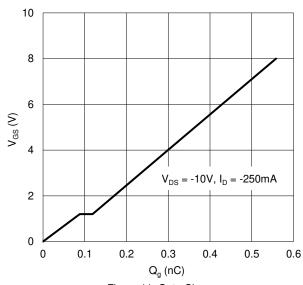


Figure 11. Gate Charge

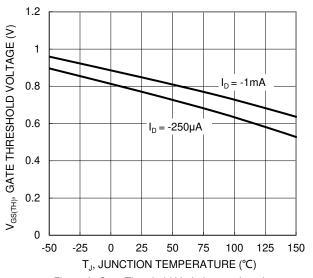


Figure 8. Gate Threshold Variation vs. Junction Temperature

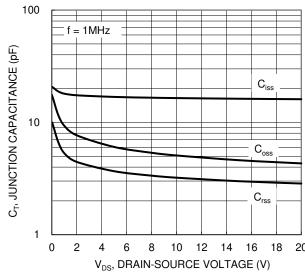


Figure 10. Typical Junction Capacitance

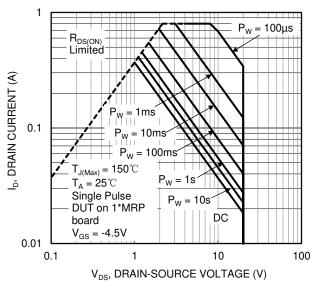


Figure 12. SOA, Safe Operation Area



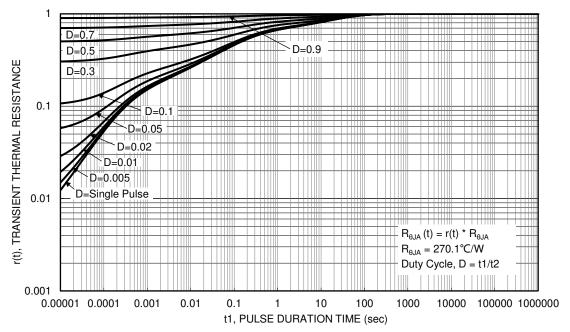


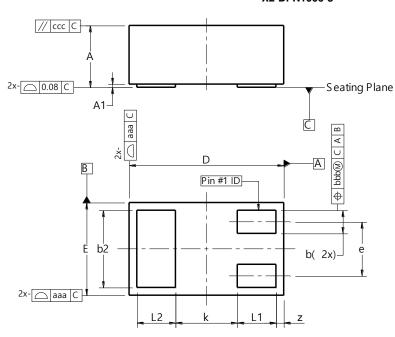
Figure 13. Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

X2-DFN1006-3

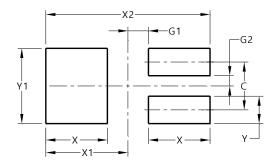


X2-DFN1006-3					
Dim	Min	Max	Тур		
Α		0.40			
A1	0.00	0.05	0.03		
b	0.10	0.20	0.15		
b2	0.45	0.55	0.50		
D	0.95	1.05	1.00		
Е	0.55	0.65	0.60		
е	ı	ı	0.35		
L1	0.20	0.30	0.25		
L2	0.20	0.30	0.25		
k	0.40				
Z	0.02 0.08 0.05				
aaa	0.15				
bbb	0.05				
CCC	0.05				
All Dimensions in mm					

Suggested Pad Layout

 $Please see \ http://www.diodes.com/package-outlines.html \ for \ the \ latest \ version.$

X2-DFN1006-3



Dimensions	Value (in mm)
С	0.350
G1	0.150
G2	0.075
X	0.450
X1	0.600
X2	1.200
Υ	0.200
V1	0.550



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